

IRF3711ZL-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, e}	Q _g (Typ)			
30	0.0034 at V _{GS} = 10 V	90	82 nC			
30	0.0070 at $V_{GS} = 4.5 \text{ V}$	70	02 110			

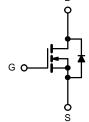
FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU









Top View

N-Channel MOSFET

APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V_{GS}	± 20	7 v	
	T _C = 25 °C		90 ^{a, e}		
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 70 °C	,	65 ^e		
Continuous Diam Current (1) = 175 C)	T _A = 25 °C	I _D	28.8 ^{b, c}	۸	
	T _A = 70 °C		27 ^{b, c}	А	
Pulsed Drain Current	I _{DM}	300			
Avalanche Current Pulse		I _{AS}	36		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	104	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	90 ^{a, e}	۸	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	Α	
	T _C = 25 °C		250 ^a		
Maximum Power Dissipation	T _C = 70 °C	ь	175	147	
	T _A = 25 °C	P _D	3.75 ^{b, c}	W	
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Тур.	Max.	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 sec	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	C/ VV	

Notes:

- a. Based on T_C = 25 °C.
 b. Surface mounted on 1" x 1" FR4 board.

- b. Surface motified of 1. X.1.1144 board.
 c. t = 10 sec.
 d. Maximum under steady state conditions is 90 °C/W.
 e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$ 30				V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = 230 μΑ		- 7.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.5		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Cata Valta na Dunin Councat		V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α
	В	V _{GS} = 10 V, I _D = 20 A		0.0034		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 20 A	0.0070			Ω
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 28.8 A		160		S
Dynamic ^b						
Input Capacitance	C _{iss}			3500		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1725		
Reverse Transfer Capacitance	C _{rss}			970		
Total Gate Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 28.8 \text{ A}$		171	257	nC
	Q_g			81.5	123	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 28.8 \text{ A}$		34		
Gate-Drain Charge	Q_{gd}			29		
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω
Turn-On Delay Time	t _{d(on)}			18	27	
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.625 Ω		11	17	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 24$ A, $V_{GEN}=10$ V, $R_g=1$ Ω		70	105	
Fall Time	t _f			10	15	no
Turn-On Delay Time	t _{d(on)}			55	83	ns -
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		180	270	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 22.5~A,~V_{GEN}=4.5~V,~R_g=1~\Omega$		55	83	
Fall Time	t _f			12	18	
Drain-Source Body Diode Characteristic	cs					
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			90	А
Pulse Diode Forward Current ^a	I _{SM}				90	^
Body Diode Voltage	V_{SD}	I _S = 22 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		70.2	105	nC
Reverse Recovery Fall Time	t _a			27		
Reverse Recovery Rise Time	t _b			25		ns

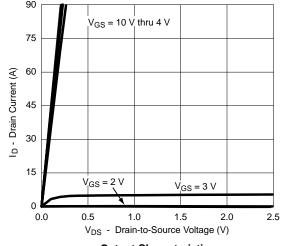
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

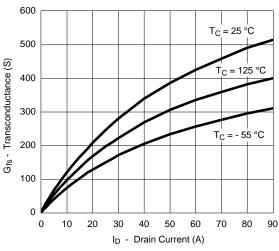
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



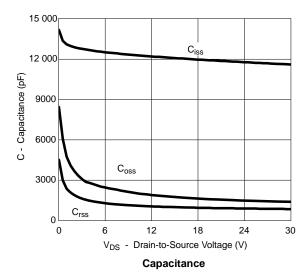
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







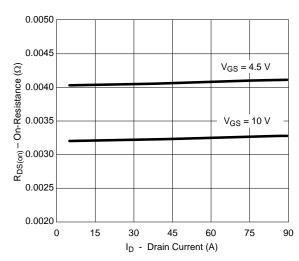
Transconductance



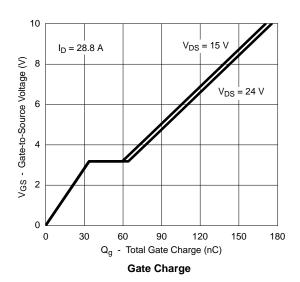
3.0

2.4 (S) (E) (E)

Transfer Characteristics

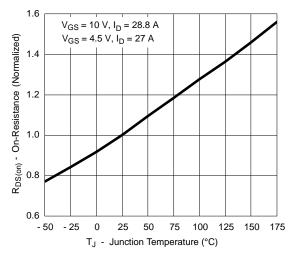


R_{DS(on)} vs. Drain Current

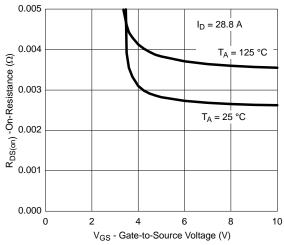




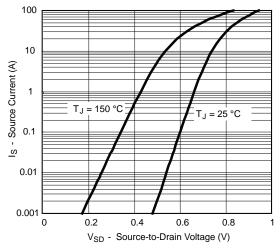
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature



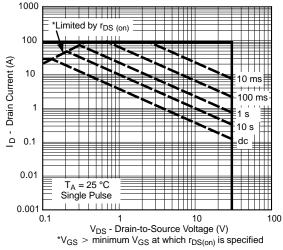
 $R_{DS(on)}$ vs. V_{GS} vs. Temperature



Forward Diode Voltage vs. Temperature



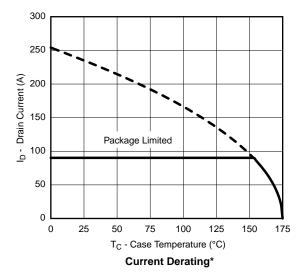
Threshold Voltage

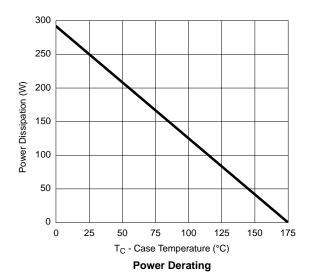


Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





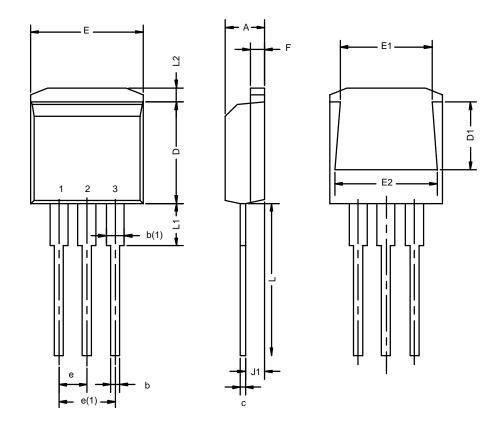
*The power dissipation P_D is based on $T_{J(max)}$ = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-262: 3-LEAD



	MILLIMETERS*		INC	HES		
Dim	Min	Max	Min	Max		
Α	4.32	4.70	0.170	0.185		
b	0.64	1.00	0.025	0.039		
b(1)	1.14	1.40	0.045	0.055		
С	0.36	0.50	0.014	0.020		
D	8.64	9.65	0.340	0.380		
D1	5.59	6.10	0.220	0.240		
е	2.41	2.67	0.095	0.105		
e(1)	4.95	5.33	0.195	0.210		
E	10.03	10.41	0.395	0.410		
E1	7.87	8.64	0.310	0.340		
E2	9.02	9.53	0.355	0.375		
F	1.14	1.40	0.045	0.055		
J1	2.41	2.79	0.095	0.110		
L	13.08	14.22	0.515	0.560		
L1	-	3.81	-	0.150		
L2	1.02	1.40	0.040	0.055		
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855						

 $^{^{\}star}$ Use millimeters as the primary measurement



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